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Intel - EP20K60EQC240-2X Datasheet



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Understanding <u>Embedded - FPGAs (Field</u> <u>Programmable Gate Array)</u>

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

Details

Details	
Product Status	Obsolete
Number of LABs/CLBs	2560
Number of Logic Elements/Cells	2560
Total RAM Bits	32768
Number of I/O	151
Number of Gates	162000
Voltage - Supply	1.71V ~ 1.89V
Mounting Type	Surface Mount
Operating Temperature	0°C ~ 85°C (TJ)
Package / Case	240-BFQFP
Supplier Device Package	240-PQFP (32x32)
Purchase URL	https://www.e-xfl.com/product-detail/intel/ep20k60eqc240-2x

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APEX 20K devices provide two dedicated clock pins and four dedicated input pins that drive register control inputs. These signals ensure efficient distribution of high-speed, low-skew control signals. These signals use dedicated routing channels to provide short delays and low skews. Four of the dedicated inputs drive four global signals. These four global signals can also be driven by internal logic, providing an ideal solution for a clock divider or internally generated asynchronous clear signals with high fan-out. The dedicated clock pins featured on the APEX 20K devices can also feed logic. The devices also feature ClockLock and ClockBoost clock management circuitry. APEX 20KE devices provide two additional dedicated clock pins, for a total of four dedicated clock pins.

MegaLAB Structure

APEX 20K devices are constructed from a series of MegaLABTM structures. Each MegaLAB structure contains a group of logic array blocks (LABs), one ESB, and a MegaLAB interconnect, which routes signals within the MegaLAB structure. The EP20K30E device has 10 LABs, EP20K60E through EP20K600E devices have 16 LABs, and the EP20K1000E and EP20K1500E devices have 24 LABs. Signals are routed between MegaLAB structures and I/O pins via the FastTrack Interconnect. In addition, edge LABs can be driven by I/O pins through the local interconnect. Figure 2 shows the MegaLAB structure.





Each LAB contains dedicated logic for driving control signals to its LEs and ESBs. The control signals include clock, clock enable, asynchronous clear, asynchronous preset, asynchronous load, synchronous clear, and synchronous load signals. A maximum of six control signals can be used at a time. Although synchronous load and clear signals are generally used when implementing counters, they can also be used with other functions.

Each LAB can use two clocks and two clock enable signals. Each LAB's clock and clock enable signals are linked (e.g., any LE in a particular LAB using CLK1 will also use CLKENA1). LEs with the same clock but different clock enable signals either use both clock signals in one LAB or are placed into separate LABs.

If both the rising and falling edges of a clock are used in a LAB, both LABwide clock signals are used.

The LAB-wide control signals can be generated from the LAB local interconnect, global signals, and dedicated clock pins. The inherent low skew of the FastTrack Interconnect enables it to be used for clock distribution. Figure 4 shows the LAB control signal generation circuit.

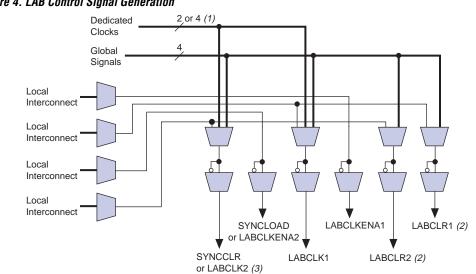


Figure 4. LAB Control Signal Generation

Notes to Figure 4:

- APEX 20KE devices have four dedicated clocks. (1)
- The LABCLR1 and LABCLR2 signals also control asynchronous load and asynchronous preset for LEs within the (2) LAB.
- (3)The SYNCCLR signal can be generated by the local interconnect or global signals.



Figure 18. Deep Memory Block Implemented with Multiple ESBs

The ESB implements two forms of dual-port memory: read/write clock mode and input/output clock mode. The ESB can also be used for bidirectional, dual-port memory applications in which two ports read or write simultaneously. To implement this type of dual-port memory, two or four ESBs are used to support two simultaneous reads or writes. This functionality is shown in Figure 19.



Each IOE drives a row, column, MegaLAB, or local interconnect when used as an input or bidirectional pin. A row IOE can drive a local, MegaLAB, row, and column interconnect; a column IOE can drive the column interconnect. Figure 27 shows how a row IOE connects to the interconnect.

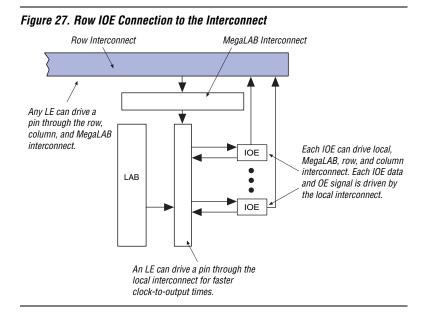
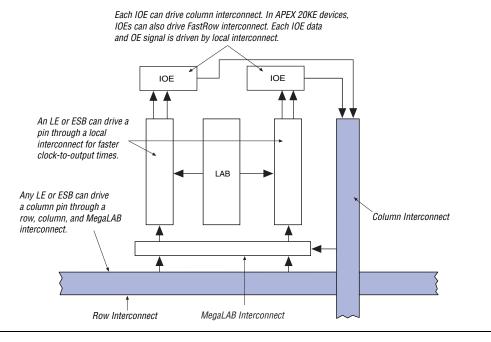


Figure 28 shows how a column IOE connects to the interconnect.

Figure 28. Column IOE Connection to the Interconnect



Dedicated Fast I/O Pins

APEX 20KE devices incorporate an enhancement to support bidirectional pins with high internal fanout such as PCI control signals. These pins are called Dedicated Fast I/O pins (FAST1, FAST2, FAST3, and FAST4) and replace dedicated inputs. These pins can be used for fast clock, clear, or high fanout logic signal distribution. They also can drive out. The Dedicated Fast I/O pin data output and tri-state control are driven by local interconnect from the adjacent MegaLAB for high speed.

Advanced I/O Standard Support

APEX 20KE IOEs support the following I/O standards: LVTTL, LVCMOS, 1.8-V I/O, 2.5-V I/O, 3.3-V PCI, PCI-X, 3.3-V AGP, LVDS, LVPECL, GTL+, CTT, HSTL Class I, SSTL-3 Class I and II, and SSTL-2 Class I and II.



For more information on I/O standards supported by APEX 20KE devices, see *Application Note* 117 (*Using Selectable I/O Standards in Altera Devices*).

The APEX 20KE device contains eight I/O banks. In QFP packages, the banks are linked to form four I/O banks. The I/O banks directly support all standards except LVDS and LVPECL. All I/O banks can support LVDS and LVPECL with the addition of external resistors. In addition, one block within a bank contains circuitry to support high-speed True-LVDS and LVPECL inputs, and another block within a particular bank supports high-speed True-LVDS and LVPECL outputs. The LVDS blocks support all of the I/O standards. Each I/O bank has its own VCCIO pins. A single device can support 1.8-V, 2.5-V, and 3.3-V interfaces; each bank can support a different standard independently. Each bank can also use a separate V_{REF} level so that each bank can support any of the terminated standards (such as SSTL-3) independently. Within a bank, any one of the terminated standards can be supported. EP20K300E and larger APEX 20KE devices support the LVDS interface for data pins (smaller devices support LVDS clock pins, but not data pins). All EP20K300E and larger devices support the LVDS interface for data pins up to 155 Mbit per channel; EP20K400E devices and larger with an X-suffix on the ordering code add a serializer/deserializer circuit and PLL for higher-speed support.

Each bank can support multiple standards with the same VCCIO for output pins. Each bank can support one voltage-referenced I/O standard, but it can support multiple I/O standards with the same VCCIO voltage level. For example, when VCCIO is 3.3 V, a bank can support LVTTL, LVCMOS, 3.3-V PCI, and SSTL-3 for inputs and outputs.

When the LVDS banks are not used as LVDS I/O banks, they support all of the other I/O standards. Figure 29 shows the arrangement of the APEX 20KE I/O banks.

For designs that require both a multiplied and non-multiplied clock, the clock trace on the board can be connected to CLK2p. Table 14 shows the combinations supported by the ClockLock and ClockBoost circuitry. The CLK2p pin can feed both the ClockLock and ClockBoost circuitry in the APEX 20K device. However, when both circuits are used, the other clock pin (CLK1p) cannot be used.

Table 14. Multiplication Factor Combinations				
Clock 1	Clock 2			
×1	×1			
×1, ×2	×2			
×1, ×2, ×4	×4			

APEX 20KE ClockLock Feature

APEX 20KE devices include an enhanced ClockLock feature set. These devices include up to four PLLs, which can be used independently. Two PLLs are designed for either general-purpose use or LVDS use (on devices that support LVDS I/O pins). The remaining two PLLs are designed for general-purpose use. The EP20K200E and smaller devices have two PLLs; the EP20K300E and larger devices have four PLLs.

The following sections describe some of the features offered by the APEX 20KE PLLs.

External PLL Feedback

The ClockLock circuit's output can be driven off-chip to clock other devices in the system; further, the feedback loop of the PLL can be routed off-chip. This feature allows the designer to exercise fine control over the I/O interface between the APEX 20KE device and another high-speed device, such as SDRAM.

Clock Multiplication

The APEX 20KE ClockBoost circuit can multiply or divide clocks by a programmable number. The clock can be multiplied by $m/(n \times k)$ or $m/(n \times v)$, where *m* and *k* range from 2 to 160, and *n* and *v* range from 1 to 16. Clock multiplication and division can be used for time-domain multiplexing and other functions, which can reduce design LE requirements.

Notes to Table 16:

- (1) To implement the ClockLock and ClockBoost circuitry with the Quartus II software, designers must specify the input frequency. The Quartus II software tunes the PLL in the ClockLock and ClockBoost circuitry to this frequency. The *f_{CLKDEV}* parameter specifies how much the incoming clock can differ from the specified frequency during device operation. Simulation does not reflect this parameter.
- (2) Twenty-five thousand parts per million (PPM) equates to 2.5% of input clock period.
- (3) During device configuration, the ClockLock and ClockBoost circuitry is configured before the rest of the device. If the incoming clock is supplied during configuration, the ClockLock and ClockBoost circuitry locks during configuration because the t_{LOCK} value is less than the time required for configuration.
- (4) The t_{IITTER} specification is measured under long-term observation.

Tables 17 and 18 summarize the ClockLock and ClockBoost parameters for APEX 20KE devices.

Table 17. APEX 20KE ClockLock & ClockBoost Parameters Note (1)								
Symbol	Parameter	Conditions	Min	Тур	Мах	Unit		
t _R	Input rise time				5	ns		
t _F	Input fall time				5	ns		
t _{INDUTY}	Input duty cycle		40		60	%		
t _{INJITTER}	Input jitter peak-to-peak				2% of input period	peak-to- peak		
t _{OUTJITTER}	Jitter on ClockLock or ClockBoost- generated clock				0.35% of output period	RMS		
t _{OUTDUTY}	Duty cycle for ClockLock or ClockBoost-generated clock		45		55	%		
t _{LOCK} (2) _, (3)	Time required for ClockLock or ClockBoost to acquire lock				40	μs		

Table 2	Table 26. APEX 20K 5.0-V Tolerant Device Capacitance Notes (2), (14)								
Symbol	Parameter	Conditions	Min	Мах	Unit				
C _{IN}	Input capacitance	V _{IN} = 0 V, f = 1.0 MHz		8	pF				
C _{INCLK}	Input capacitance on dedicated clock pin	V _{IN} = 0 V, f = 1.0 MHz		12	pF				
C _{OUT}	Output capacitance	V _{OUT} = 0 V, f = 1.0 MHz		8	pF				

Notes to Tables 23 through 26:

- (1) See the Operating Requirements for Altera Devices Data Sheet.
- All APEX 20K devices are 5.0-V tolerant. (2)
- (3) Minimum DC input is -0.5 V. During transitions, the inputs may undershoot to -2.0 V or overshoot to 5.75 V for input currents less than 100 mA and periods shorter than 20 ns.
- Numbers in parentheses are for industrial-temperature-range devices. (4)
- Maximum V_{CC} rise time is 100 ms, and V_{CC} must rise monotonically. (5)
- All pins, including dedicated inputs, clock I/O, and JTAG pins, may be driven before V_{CCINT} and V_{CCIO} are (6) powered.
- (7)Typical values are for $T_A = 25^{\circ}$ C, $V_{CCINT} = 2.5$ V, and $V_{CCIO} = 2.5$ or 3.3 V.
- These values are specified in the APEX 20K device recommended operating conditions, shown in Table 26 on (8)page 62.
- (9) The APEX 20K input buffers are compatible with 2.5-V and 3.3-V (LVTTL and LVCMOS) signals. Additionally, the input buffers are 3.3-V PCI compliant when V_{CCIO} and V_{CCINT} meet the relationship shown in Figure 33 on page 68.
- (10) The I_{OH} parameter refers to high-level TTL, PCI or CMOS output current.
- (11) The I_{OL} parameter refers to low-level TTL, PCI, or CMOS output current. This parameter applies to open-drain pins as well as output pins.
- (12) This value is specified for normal device operation. The value may vary during power-up.
- (13) Pin pull-up resistance values will be lower if an external source drives the pin higher than V_{CCIO} .
- (14) Capacitance is sample-tested only.

Tables 27 through 30 provide information on absolute maximum ratings, recommended operating conditions, DC operating conditions, and capacitance for 1.8-V APEX 20KE devices.

Symbol	Parameter	Conditions	Min	Max	Unit
V _{CCINT}	Supply voltage	With respect to ground (2)	-0.5	2.5	V
V _{CCIO}			-0.5	4.6	V
VI	DC input voltage		-0.5	4.6	V
I _{OUT}	DC output current, per pin		-25	25	mA
T _{STG}	Storage temperature	No bias	-65	150	°C
T _{AMB}	Ambient temperature	Under bias	-65	135	°C
ΤJ	Junction temperature	PQFP, RQFP, TQFP, and BGA packages, under bias		135	°C
		Ceramic PGA packages, under bias		150	°C

Table 2	8. APEX 20KE Device Recommende	ed Operating Conditions			
Symbol	Parameter	Conditions	Min	Max	Unit
V _{CCINT}	Supply voltage for internal logic and input buffers	(3), (4)	1.71 (1.71)	1.89 (1.89)	V
V _{CCIO}	Supply voltage for output buffers, 3.3-V operation	(3), (4)	3.00 (3.00)	3.60 (3.60)	V
	Supply voltage for output buffers, 2.5-V operation	(3), (4)	2.375 (2.375)	2.625 (2.625)	V
	Supply voltage for output buffers, 1.8-V operation	(3), (4)	1.71 (1.71)	1.89 (1.89)	V
VI	Input voltage	(5), (6)	-0.5	4.0	V
Vo	Output voltage		0	V _{CCIO}	V
ТJ	Junction temperature	For commercial use	0	85	°C
		For industrial use	-40	100	°C
t _R	Input rise time			40	ns
t _F	Input fall time			40	ns

Table 36. APE	Table 36. APEX 20KE Routing Timing Microparameters Note (1)							
Symbol	Parameter							
t _{F1-4}	Fanout delay using Local Interconnect							
t _{F5-20}	Fanout delay estimate using MegaLab Interconnect							
t _{F20+}	Fanout delay estimate using FastTrack Interconnect							

Note to Table 36:

 These parameters are worst-case values for typical applications. Post-compilation timing simulation and timing analysis are required to determine actual worst-case performance.

Symbol	EX 20KE Functional Timing Microparameters Parameter
Symbol	i alainetei
тсн	Minimum clock high time from clock pin
TCL	Minimum clock low time from clock pin
TCLRP	LE clear Pulse Width
TPREP	LE preset pulse width
TESBCH	Clock high time for ESB
TESBCL	Clock low time for ESB
TESBWP	Write pulse width
TESBRP	Read pulse width

Table 37. APEX 20KE Functional Timing Microparameters

Tables 38 and 39 describe the APEX 20KE external timing parameters.

Table 38. APEX 20KE External Timing Parameters Note (1)						
Symbol	Conditions					
t _{INSU}	Setup time with global clock at IOE input register					
t _{INH}	Hold time with global clock at IOE input register					
t _{оитсо}	Clock-to-output delay with global clock at IOE output register	C1 = 10 pF				
t _{INSUPLL}	Setup time with PLL clock at IOE input register					
t _{INHPLL}	Hold time with PLL clock at IOE input register					
t _{OUTCOPLL}	Clock-to-output delay with PLL clock at IOE output register	C1 = 10 pF				

Symbol	-1 Speed Grade		-2 Speed Grade		-3 Speed Grade		Units
	Min	Мах	Min	Max	Min	Max	
t _{SU}	0.5		0.6		0.8		ns
t _H	0.7		0.8		1.0		ns
t _{co}		0.3		0.4		0.5	ns
t _{lut}		0.8		1.0		1.3	ns
t _{ESBRC}		1.7		2.1		2.4	ns
t _{ESBWC}		5.7		6.9		8.1	ns
t _{ESBWESU}	3.3		3.9		4.6		ns
t _{ESBDATASU}	2.2		2.7		3.1		ns
t _{ESBDATAH}	0.6		0.8		0.9		ns
t _{ESBADDRSU}	2.4		2.9		3.3		ns
t _{ESBDATACO1}		1.3		1.6		1.8	ns
t _{ESBDATACO2}		2.6		3.1		3.6	ns
t _{ESBDD}		2.5		3.3		3.6	ns
t _{PD}		2.5		3.0		3.6	ns
t _{PTERMSU}	2.3		2.7		3.2		ns
t _{PTERMCO}		1.5		1.8		2.1	ns
t _{F1-4}		0.5		0.6		0.7	ns
t _{F5-20}		1.6		1.7		1.8	ns
t _{F20+}		2.2		2.2		2.3	ns
t _{CH}	2.0		2.5		3.0		ns
t _{CL}	2.0		2.5		3.0		ns
t _{CLRP}	0.3		0.4		0.4		ns
t _{PREP}	0.4		0.5		0.5		ns
t _{ESBCH}	2.0		2.5		3.0		ns
t _{ESBCL}	2.0		2.5		3.0		ns
t _{ESBWP}	1.6		1.9		2.2		ns
t _{ESBRP}	1.0		1.3		1.4		ns

Symbol	-	-1		-2		-3	
	Min	Max	Min	Max	Min	Max	
t _{ESBARC}		1.83		2.57		3.79	ns
t _{ESBSRC}		2.46		3.26		4.61	ns
t _{ESBAWC}		3.50		4.90		7.23	ns
t _{ESBSWC}		3.77		4.90		6.79	ns
t _{ESBWASU}	1.59		2.23		3.29		ns
t _{ESBWAH}	0.00		0.00		0.00		ns
t _{ESBWDSU}	1.75		2.46		3.62		ns
t _{ESBWDH}	0.00		0.00		0.00		ns
t _{ESBRASU}	1.76		2.47		3.64		ns
t _{ESBRAH}	0.00		0.00		0.00		ns
t _{ESBWESU}	1.68		2.49		3.87		ns
t _{ESBWEH}	0.00		0.00		0.00		ns
t _{ESBDATASU}	0.08		0.43		1.04		ns
t _{ESBDATAH}	0.13		0.13		0.13		ns
t _{ESBWADDRSU}	0.29		0.72		1.46		ns
t _{ESBRADDRSU}	0.36		0.81		1.58		ns
t _{ESBDATACO1}		1.06		1.24		1.55	ns
t _{ESBDATACO2}		2.39		3.35		4.94	ns
t _{ESBDD}		3.50		4.90		7.23	ns
t _{PD}		1.72		2.41		3.56	ns
t _{PTERMSU}	0.99		1.56		2.55		ns
t _{PTERMCO}		1.07		1.26		1.08	ns

Symbol	-1		-	-2		-3	
	Min	Max	Min	Max	Min	Max	
t _{ESBARC}		1.68		2.06		2.24	ns
t _{ESBSRC}		2.27		2.77		3.18	ns
t _{ESBAWC}		3.10		3.86		4.50	ns
t _{ESBSWC}		2.90		3.67		4.21	ns
t _{ESBWASU}	0.55		0.67		0.74		ns
t _{ESBWAH}	0.36		0.46		0.48		ns
t _{ESBWDSU}	0.69		0.83		0.95		ns
t _{ESBWDH}	0.36		0.46		0.48		ns
t _{ESBRASU}	1.61		1.90		2.09		ns
t _{ESBRAH}	0.00		0.00		0.01		ns
t _{ESBWESU}	1.42		1.71		2.01		ns
t _{ESBWEH}	0.00		0.00		0.00		ns
t _{ESBDATASU}	-0.06		-0.07		0.05		ns
t _{ESBDATAH}	0.13		0.13		0.13		ns
t _{ESBWADDRSU}	0.11		0.13		0.31		ns
t _{ESBRADDRSU}	0.18		0.23		0.39		ns
t _{ESBDATACO1}		1.09		1.35		1.51	ns
t _{ESBDATACO2}		2.19		2.75		3.22	ns
t _{ESBDD}		2.75		3.41		4.03	ns
t _{PD}		1.58		1.97		2.33	ns
t _{PTERMSU}	1.00		1.22		1.51		ns
t _{PTERMCO}		1.10		1.37		1.09	ns

Table 75. EP2	Table 75. EP20K200E f _{MAX} Routing Delays									
Symbol	-1			-2		-3				
	Min	Max	Min	Max	Min	Max				
t _{F1-4}		0.25		0.27		0.29	ns			
t _{F5-20}		1.02		1.20		1.41	ns			
t _{F20+}		1.99		2.23		2.53	ns			

Symbol -1 Min	1	-2		-3	Unit		
	Min	Max	Min	Max	Min	Max	
t _{CH}	1.25		1.43		1.67		ns
t _{CL}	1.25		1.43		1.67		ns
t _{CLRP}	0.19		0.26		0.35		ns
t _{PREP}	0.19		0.26		0.35		ns
t _{ESBCH}	1.25		1.43		1.67		ns
t _{ESBCL}	1.25		1.43		1.67		ns
t _{ESBWP}	1.25		1.71		2.28		ns
t _{ESBRP}	1.01		1.38		1.84		ns

Symbol	-1		-	2	-3	Unit	
	Min	Мах	Min	Max	Min	Max	
t _{INSU}	2.31		2.44		2.57		ns
t _{INH}	0.00		0.00		0.00		ns
t _{outco}	2.00	5.29	2.00	5.82	2.00	6.24	ns
t _{insupll}	1.76		1.85		-		ns
t _{INHPLL}	0.00		0.00		-		ns
toutcopll	0.50	2.65	0.50	2.95	-	-	ns

Symbol	-1		-2		-3		Unit	
	Min	Max	Min	Max	Min	Max]	
t _{insubidir}	2.77		2.85		3.11		ns	
t _{inhbidir}	0.00		0.00		0.00		ns	
toutcobidir	2.00	5.29	2.00	5.82	2.00	6.24	ns	
t _{xzbidir}		7.59		8.30		9.09	ns	
t _{zxbidir}		7.59		8.30		9.09	ns	
t _{insubidirpll}	2.50		2.76		-		ns	
t _{inhbidirpll}	0.00		0.00		-		ns	
toutcobidirpll	0.50	2.65	0.50	2.95	-	-	ns	
t _{XZBIDIRPLL}		5.00		5.43		-	ns	
t _{ZXBIDIRPLL}		5.00		5.43		-	ns	

Symbol	-1 Spee	d Grade	-2 Spee	ed Grade	-3 Spee	d Grade	Unit
	Min	Max	Min	Max	Min	Max	
t _{ESBARC}		1.67		2.39		3.11	ns
t _{ESBSRC}		2.27		3.07		3.86	ns
t _{ESBAWC}		3.19		4.56		5.93	ns
t _{ESBSWC}		3.51		4.62		5.72	ns
t _{ESBWASU}	1.46		2.08		2.70		ns
t _{ESBWAH}	0.00		0.00		0.00		ns
t _{ESBWDSU}	1.60		2.29		2.97		ns
t _{ESBWDH}	0.00		0.00		0.00		ns
t _{ESBRASU}	1.61		2.30		2.99		ns
t _{ESBRAH}	0.00		0.00		0.00		ns
t _{ESBWESU}	1.49		2.30		3.11		ns
t _{ESBWEH}	0.00		0.00		0.00		ns
t _{ESBDATASU}	-0.01		0.35		0.71		ns
t _{ESBDATAH}	0.13		0.13		0.13		ns
t _{ESBWADDRSU}	0.19		0.62		1.06		ns
t _{ESBRADDRSU}	0.25		0.71		1.17		ns
t _{ESBDATACO1}		1.01		1.19		1.37	ns
t _{ESBDATACO2}		2.18		3.12		4.05	ns
t _{ESBDD}		3.19		4.56		5.93	ns
t _{PD}		1.57		2.25		2.92	ns
t _{PTERMSU}	0.85		1.43		2.01		ns
t _{PTERMCO}		1.03		1.21		1.39	ns

Table 93. EP2	Table 93. EP20K600E f _{MAX} Routing Delays									
Symbol	-1 Speed Grade		-2 Spe	-2 Speed Grade		d Grade	Unit			
	Min	Max	Min	Max	Min	Мах				
t _{F1-4}		0.22		0.25		0.26	ns			
t _{F5-20}		1.26		1.39		1.52	ns			
t _{F20+}		3.51		3.88		4.26	ns			

Symbol	-1 Spee	d Grade	-2 Spee	ed Grade	-3 Spee	d Grade	Unit
	Min	Max	Min	Max	Min	Max	
t _{ESBARC}		1.78		2.02		1.95	ns
t _{ESBSRC}		2.52		2.91		3.14	ns
t _{ESBAWC}		3.52		4.11		4.40	ns
t _{ESBSWC}		3.23		3.84		4.16	ns
t _{ESBWASU}	0.62		0.67		0.61		ns
t _{ESBWAH}	0.41		0.55		0.55		ns
t _{ESBWDSU}	0.77		0.79		0.81		ns
t _{ESBWDH}	0.41		0.55		0.55		ns
t _{ESBRASU}	1.74		1.92		1.85		ns
t _{ESBRAH}	0.00		0.01		0.23		ns
t _{ESBWESU}	2.07		2.28		2.41		ns
t _{ESBWEH}	0.00		0.00		0.00		ns
t _{ESBDATASU}	0.25		0.27		0.29		ns
t _{ESBDATAH}	0.13		0.13		0.13		ns
t _{ESBWADDRSU}	0.11		0.04		0.11		ns
t _{ESBRADDRSU}	0.14		0.11		0.16		ns
t _{ESBDATACO1}		1.29		1.50		1.63	ns
t _{ESBDATACO2}		2.55		2.99		3.22	ns
t _{ESBDD}		3.12		3.57		3.85	ns
t _{PD}		1.84		2.13		2.32	ns
t _{PTERMSU}	1.08		1.19		1.32		ns
t _{PTERMCO}		1.31		1.53		1.66	ns

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Symbol	-1 Spee	d Grade	-2 Spee	ed Grade	-3 Spee	d Grade	Unit
	Min	Max	Min	Max	Min	Мах	
t _{ESBARC}		1.78		2.02		1.95	ns
t _{ESBSRC}		2.52		2.91		3.14	ns
t _{ESBAWC}		3.52		4.11		4.40	ns
t _{ESBSWC}		3.23		3.84		4.16	ns
t _{ESBWASU}	0.62		0.67		0.61		ns
t _{ESBWAH}	0.41		0.55		0.55		ns
t _{ESBWDSU}	0.77		0.79		0.81		ns
t _{ESBWDH}	0.41		0.55		0.55		ns
t _{ESBRASU}	1.74		1.92		1.85		ns
t _{ESBRAH}	0.00		0.01		0.23		ns
t _{ESBWESU}	2.07		2.28		2.41		ns
t _{ESBWEH}	0.00		0.00		0.00		ns
t _{ESBDATASU}	0.25		0.27		0.29		ns
t _{ESBDATAH}	0.13		0.13		0.13		ns
t _{ESBWADDRSU}	0.11		0.04		0.11		ns
t _{ESBRADDRSU}	0.14		0.11		0.16		ns
t _{ESBDATACO1}		1.29		1.50		1.63	ns
t _{ESBDATACO2}		2.55		2.99		3.22	ns
t _{ESBDD}		3.12		3.57		3.85	ns
t _{PD}		1.84		2.13		2.32	ns
t _{PTERMSU}	1.08		1.19		1.32		ns
t _{PTERMCO}		1.31		1.53		1.66	ns

Table 105. EP.	Table 105. EP20K1500E f _{MAX} Routing Delays									
Symbol	-1 Speed Grade		-2 Spec	-2 Speed Grade		d Grade	Unit			
	Min	Max	Min	Мах	Min	Max				
t _{F1-4}		0.28		0.28		0.28	ns			
t _{F5-20}		1.36		1.50		1.62	ns			
t _{F20+}		4.43		4.48		5.07	ns			

Table 108. EP20K1500E External Bidirectional Timing Parameters							
Symbol	-1 Spee	d Grade	-2 Spee	d Grade	-3 Spee	ed Grade	Unit
	Min	Max	Min	Max	Min	Max	
t _{insubidir}	3.47		3.68		3.99		ns
t _{inhbidir}	0.00		0.00		0.00		ns
t _{outcobidir}	2.00	6.18	2.00	6.81	2.00	7.36	ns
t _{XZBIDIR}		6.91		7.62		8.38	ns
t _{ZXBIDIR}		6.91		7.62		8.38	ns
t _{insubidirpll}	3.05		3.26				ns
t _{inhbidirpll}	0.00		0.00				ns
t _{outcobidirpll}	0.50	2.67	0.50	2.99			ns
t _{xzbidirpll}		3.41		3.80			ns
t _{ZXBIDIRPLL}		3.41		3.80			ns

Tables 109 and 110 show selectable I/O standard input and output delays for APEX 20KE devices. If you select an I/O standard input or output delay other than LVCMOS, add or subtract the selected speed grade to or from the LVCMOS value.

Table 109. Selectable I/O Standard Input Delays							
Symbol	-1 Spee	ed Grade	-2 Spe	ed Grade	-3 Spee	d Grade	Unit
	Min	Max	Min	Max	Min	Max	Min
LVCMOS		0.00		0.00		0.00	ns
LVTTL		0.00		0.00		0.00	ns
2.5 V		0.00		0.04		0.05	ns
1.8 V		-0.11		0.03		0.04	ns
PCI		0.01		0.09		0.10	ns
GTL+		-0.24		-0.23		-0.19	ns
SSTL-3 Class I		-0.32		-0.21		-0.47	ns
SSTL-3 Class II		-0.08		0.03		-0.23	ns
SSTL-2 Class I		-0.17		-0.06		-0.32	ns
SSTL-2 Class II		-0.16		-0.05		-0.31	ns
LVDS		-0.12		-0.12		-0.12	ns
CTT		0.00		0.00		0.00	ns
AGP		0.00		0.00		0.00	ns

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SRAM configuration elements allow APEX 20K devices to be reconfigured in-circuit by loading new configuration data into the device. Real-time reconfiguration is performed by forcing the device into command mode with a device pin, loading different configuration data, reinitializing the device, and resuming usermode operation. In-field upgrades can be performed by distributing new configuration files.

Configuration Schemes

The configuration data for an APEX 20K device can be loaded with one of five configuration schemes (see Table 111), chosen on the basis of the target application. An EPC2 or EPC16 configuration device, intelligent controller, or the JTAG port can be used to control the configuration of an APEX 20K device. When a configuration device is used, the system can configure automatically at system power-up.

Multiple APEX 20K devices can be configured in any of five configuration schemes by connecting the configuration enable (nCE) and configuration enable output (nCEO) pins on each device.

Table 111. Data Sources for Configura	ntion
Configuration Scheme	Data Source
Configuration device	EPC1, EPC2, EPC16 configuration devices
Passive serial (PS)	MasterBlaster or ByteBlasterMV download cable or serial data source
Passive parallel asynchronous (PPA)	Parallel data source
Passive parallel synchronous (PPS)	Parallel data source
JTAG	MasterBlaster or ByteBlasterMV download cable or a microprocessor
	with a Jam or JBC File



For more information on configuration, see *Application Note* 116 (*Configuring APEX 20K, FLEX 10K, & FLEX 6000 Devices.*)

Device Pin-Outs

See the Altera web site (http://www.altera.com) or the *Altera Digital Library* for pin-out information